UPDATE CHANGE NOTIFICATION # 16523

Generic Copy

Issue Date: 16-Sep-2010

TITLE: Update Notification to Product Discontinuance #16389

PROPOSED FIRST SHIP DATE: 16-Sep-2010

AFFECTED CHANGE CATEGORY(S): EOL

ADDITIONAL RELIABILITY DATA: N/A

SAMPLES: N/A

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Scott Brow<Scott.Brow@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This notification is to inform our customers of the discontinuance of the device listed in this document. It was inadvertently omitted from Product Discontinuance #16389. The product was to be discontinued due to the End of Life of the mold tool used to assemble the device. As such, at this time, ON Semiconductor can no longer produce this package. The product is available in an SOIC-16WB package.

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List of affected General Parts:

Part ID	Replacement Device	Replacement Device Supplier
MC33363APG	MC33363DWR2G	ON Semiconductor